

1. — (Amended) Components A component, comprising:  
characterized by

2. (Amended)                      The                      Components                      of                      claim 1,  
wherein characterized in that the edge of the glass cover  
has been superficially roughened.

3. (Amended) The components of claim 1—~~or—~~2, wherein~~characterized in that~~ the glass cover is bonded to the glass substrate using an organic adhesive.

4. (Amended) The cComponents of claim 3,  
wherein ~~characterized in that~~ the adhesive is UV-curable.

5. (Amended) The components of claim 3—~~or~~—4,  
wherein characterized in that the adhesive is an epoxy  
resin.

- 6.6.-(Amended) A process for producing a ~~components of one~~  
~~or more of claims 1 to 5,~~ comprising:

~~producing a plurality characterized in that a large~~  
~~number of recesses is produced in a glass plate by three-~~  
dimensional removal of material using a sandblasting  
method using commercial crystal corundum having an  
average particle size of 30  $\mu\text{m}$  and a blasting pressure of

99 P 3623

5 bar, said recesses having edges protected by ~~in each~~  
~~ease one~~ a resist layer<sub>7</sub>;

~~removing then~~ the protective layer of the edges ~~is~~  
~~removed~~; and

~~subjecting~~ the edges of the recesses, lying bare, ~~are~~  
~~subjected~~ to a further sandblasting method using corundum  
having an average particle size of 9  $\mu$ m and a blasting  
pressure of only 3 bar.

7. (Amended) The process of claim 6, wherein an injector  
blasting nozzle is used as blasting nozzle in the  
initial~~first~~ sandblasting method.

8. (Amended) The process of ~~one of~~ claims 6 ~~or~~ 7, wherein  
the distance between nozzle and workpiece in the initial  
~~first~~ sandblasting method is 80 mm.

9. The process of ~~one of~~ claims 6 ~~to~~ 8, wherein edges having  
a roughness of about 30 rms are produced

99 P 3623

in the further ~~second sand~~blasting method in a blasting time of 30 seconds.

10. (Amended) The process of ~~one of claims 6 to 9~~, wherein after the recesses have been manufactured, the glass plate is used in order to encapsulate a corresponding number of organic light-emitting diodes arranged correspondingly on a substrate, and wherein, following the encapsulation, the resultant components are at least partly individualized.

#### New Claims

11. The process of claim 6, further comprising:  
encapsulating ~~in that using this glass plate a~~  
 corresponding number of organic light-emitting diodes  
 arranged correspondingly on a substrate using the glass  
plate, wherein is encapsulated, and in that subse-



99 P 3623

Abstract

~~Components and their production~~

~~The~~A ~~components of the invention comprise the following elements:~~ includes

a glass substrate, ~~(11)~~

an organic light-emitting diode ~~(12)~~ arranged on the~~said~~ glass substrate ~~(11)~~, and

a glass cover ~~(13)~~ ~~which is~~ arranged over the organic light-emitting diode ~~(12)~~. The glass cover ~~and~~ is glued at the edge ~~(14)~~ to the glass substrate. The ~~(11)~~, ~~said~~ cover is

one~~being~~ produced from a glass plate by three-dimensional removal of material using a blasting method.

~~FIG 1~~

19-09-2001  
PCT/DE 00/03108

- 1 -

DE00031  
16.09/01

New claims 1 and 6 to 10

1. Components, characterized by
  - a glass substrate (1)
  - 5 • an organic light-emitting diode (12) arranged on said glass substrate (11), and
  - a glass cover (13) which is arranged over the organic light-emitting diode (12) and is glued at the edge (14) to the glass substrate (11),  
10 said cover being produced from a glass plate by three-dimensional removal of material using a sandblasting method using commercial crystal corundum having an average particle size of 30  $\mu$ m and a blasting pressure of 5 bar.
- 15 6. A process for producing components of one or more of claims 1 to 5, characterized in that a large number of recesses is produced in a glass plate by three-dimensional removal of material using a  
20 sandblasting method using commercial crystal corundum having an average particle size of 30  $\mu$ m and a blasting pressure of 5 bar, said recesses having edges protected by in each case one resist layer, then the protective layer of the edges is removed and the edges of the recesses, lying bare,  
25 are subjected to a further sandblasting method using corundum having an average particle size of 9  $\mu$ m and a blasting pressure of only 3 bar.
- 30 7. The process of claim 6, wherein an injector blasting nozzle is used as blasting nozzle in the first sandblasting method.
- 35 8. The process of one of claims 6 or 7, wherein the distance between nozzle and workpiece in the first sandblasting method is 80 mm.
9. The process of one of claims 6 to 8, wherein edges having a roughness of about 30 rms are produced

AMENDED SHEET

19-09-2001  
PCT/DE 00/03108

- 2 -

DE0003108  
16.09.01

in the second sandblasting method in a blasting  
time of 30 seconds.

- 5      10. The process of one of claims 6 to 9, wherein after  
the recesses have been manufactured the glass  
plate is used in order to encapsulate a corres-  
ponding number of organic light-emitting diodes  
arranged correspondingly on a substrate and where  
following the encapsulation the resultant com-  
10      ponents are at least partly individualized.